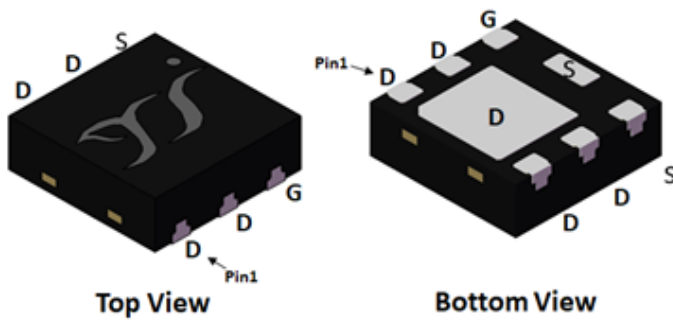
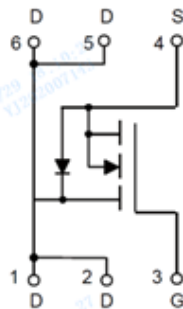


N-Channel Enhancement Mode Field Effect Transistor



DFN2020-6L-WF



Product Summary

• V_{DS}	20V
• I_D	27A
• $R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 15m Ω
• $R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 20m Ω
• $R_{DS(ON)}$ (at $V_{GS}=1.8V$)	< 30m Ω
• ESD Level(HBM)	H1A

General Description

- Package with side-wettable flanks
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Power switching application
- Uninterruptible power supply
- DC-DC convertor

Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			V _{DS}	-	20	V
Gate-source Voltage			V _{GS}	-10	10	
Continuous Drain Current (Note 1,2)	Steady-State	T _A =25°C,V _{GS} =10V	I _D	-	8.2	A
		T _A =100°C,V _{GS} =10V		-	5.2	
Continuous Drain Current (Note 1,3)	Steady-State	T _C =25°C,V _{GS} =10V,Chip limitation		-	27	
		T _C =100°C,V _{GS} =10V		-	17	
Pulsed Drain Current	T _C =25 °C ,t _p ≤10μs		I _{DM}	-	108	
Maximum Body-Diode Continuous Current	T _C =25 °C		I _S		15	
Total Power Dissipation (Note 1,2)	Steady-State	T _A =25°C	P _D	-	1.6	W
		T _A =100°C		-	0.6	
Total Power Dissipation (Note 1,3)	Steady-State	T _C =25°C		-	17	
		T _C =100°C		-	6.8	
Junction and Storage Temperature Range			T _J ,T _{STG}	-55	150	°C

Thermal Resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	78	$^{\circ}C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	7.3	

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQT015N02AQ	F1	015N02	3000	30000	120000	7" reel



YJQT015N02AQ

■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A, T_j=25^{\circ}C$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V, T_j=25^{\circ}C$	-	-	1	μA
		$V_{DS}=20V, V_{GS}=0V, T_j=125^{\circ}C$	-	-	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V, T_j=25^{\circ}C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A, T_j=25^{\circ}C$	0.4	0.7	1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=9A, T_j=25^{\circ}C$	-	12	15	m Ω
		$V_{GS}=2.5V, I_D=5A, T_j=25^{\circ}C$	-	15	20	m Ω
		$V_{GS}=1.8V, I_D=2.5A, T_j=25^{\circ}C$	-	21	30	m Ω
Diode Forward Voltage	V_{SD}	$I_S=9A, V_{GS}=0V, T_j=25^{\circ}C$	-	0.84	1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^{\circ}C$	-	2.4	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V, f=1MHz, T_j=25^{\circ}C$	-	680	-	pF
Output Capacitance	C_{oss}		-	115	-	
Reverse Transfer Capacitance	C_{rss}		-	105	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=4.5V, V_{DS}=10V, I_D=9A, T_j=25^{\circ}C$	-	9	-	nC
Gate-Source Charge	Q_{gs}		-	0.5	-	
Gate-Drain Charge	Q_{gd}		-	2.4	-	
Reverse Recovery Charge	Q_{rr}	$I_F=9A, di/dt=100A/\mu s, V_{GS}=0V, V_R=10V, T_j=25^{\circ}C$	-	1.8	-	nC
Reverse Recovery Time	t_{rr}		-	439	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=4.5V, V_{DS}=10V, I_D=9A, R_{GEN}=3\Omega, T_j=25^{\circ}C$	-	12	-	ns
Turn-on Rise Time	t_r		-	51	-	
Turn-off Delay Time	$t_{D(off)}$		-	30	-	
Turn-off Fall Time	t_f		-	10	-	

Note:

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of $150^\circ C$. The value in any given application depends on the user's specific board design.
3. Thermal resistance from junction to soldering point (on the exposed drain pad).



■ Typical Electrical and Thermal Characteristics Diagrams

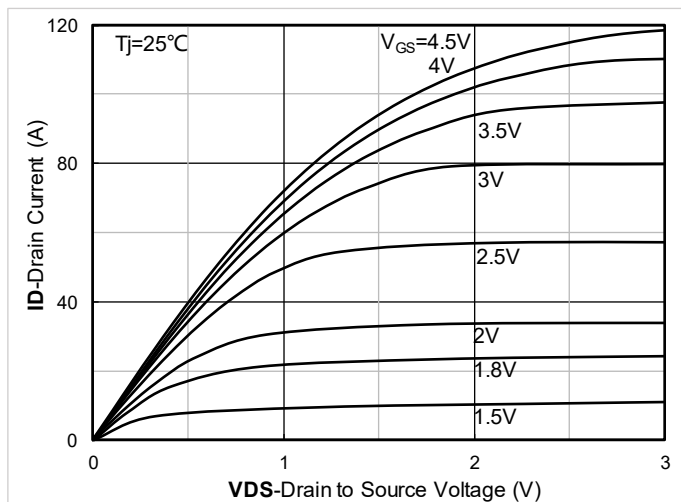


Figure 1. Output Characteristics; typical values

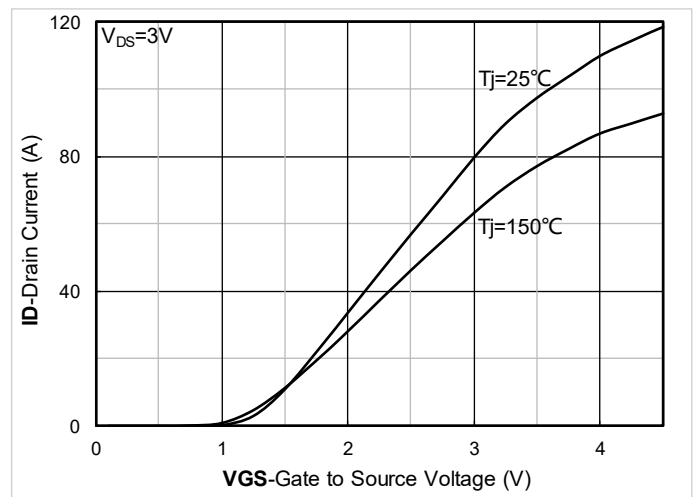


Figure 2. Transfer Characteristics; typical values

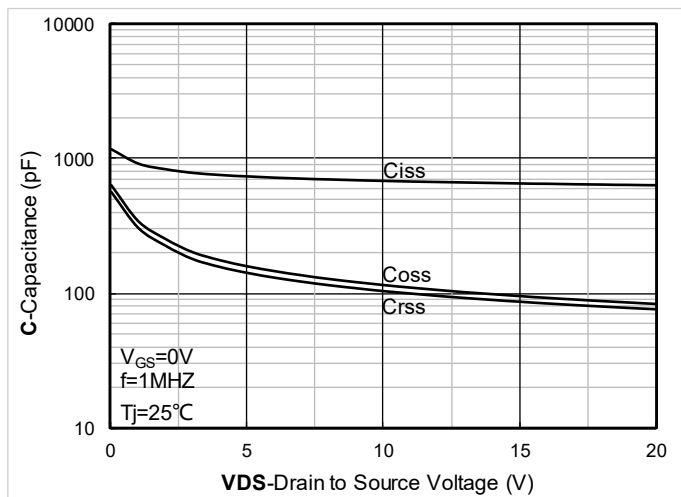


Figure 3. Capacitance Characteristics; typical values

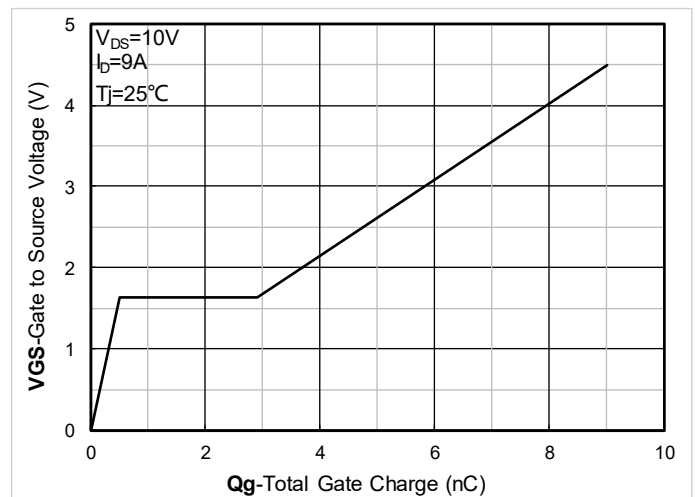


Figure 4. Gate Charge; typical values

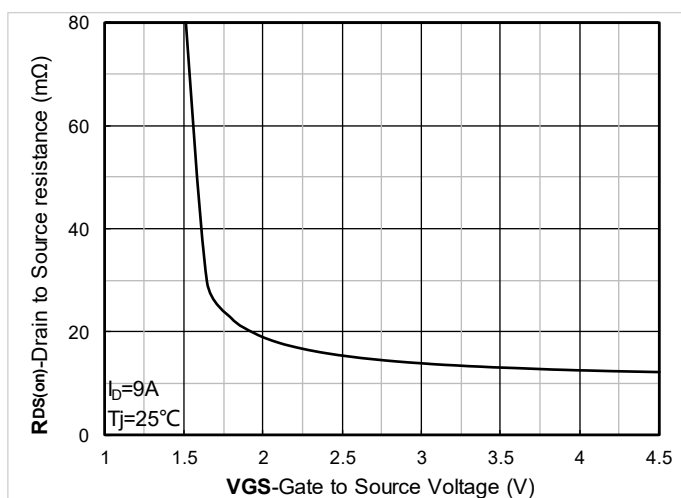


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

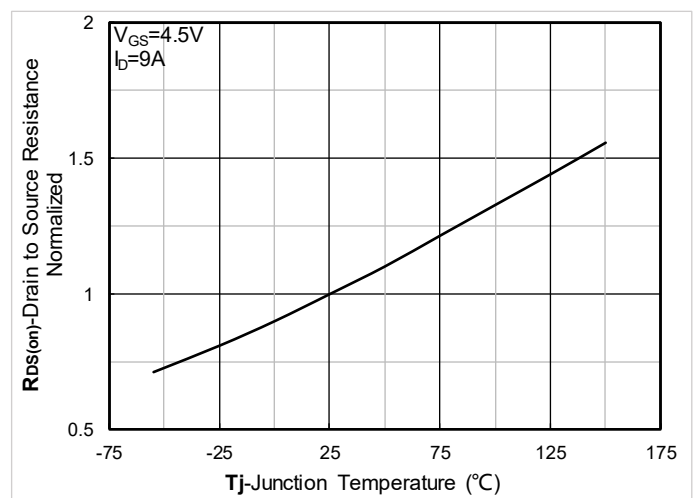


Figure 6. Normalized On-Resistance

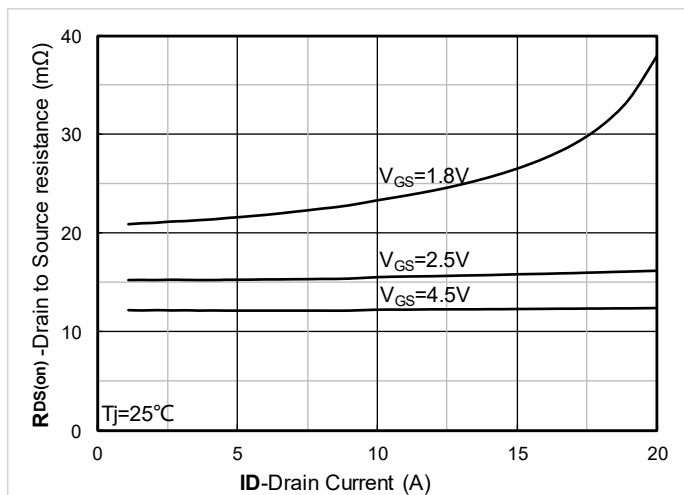


Figure 7. RDS(on) vs. Drain Current; typical values

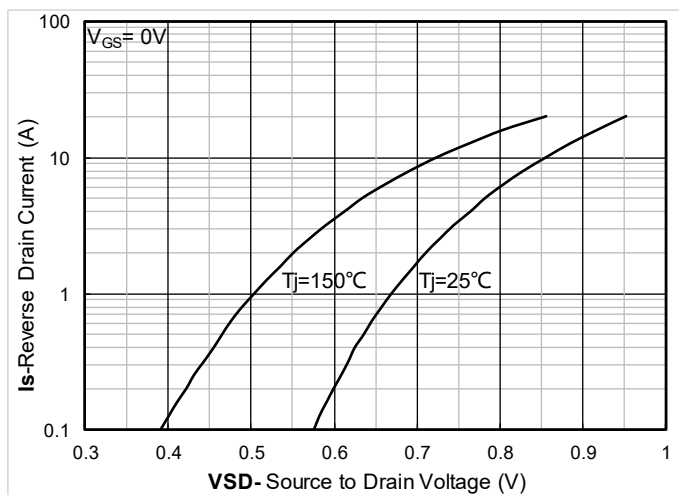


Figure 8. Forward characteristics of reverse diode; typical values

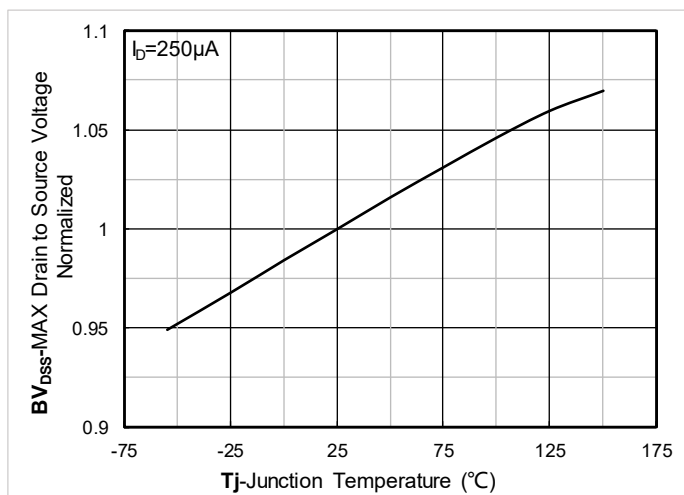


Figure 9. Normalized breakdown voltage

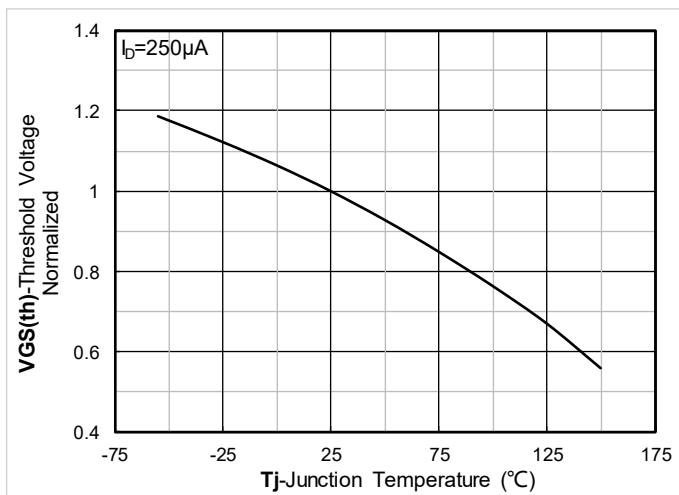


Figure 10. Normalized Threshold voltage

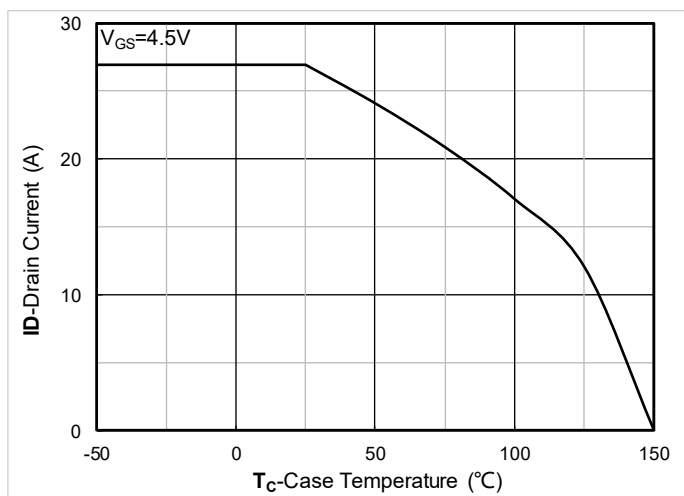


Figure 11. Current dissipation

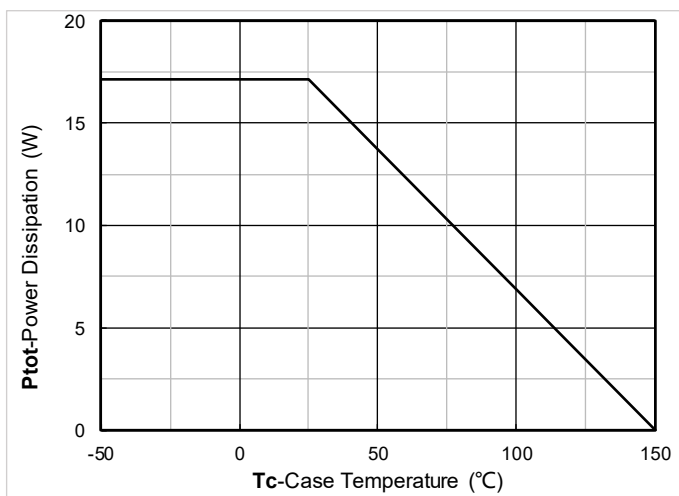


Figure 12. Power dissipation

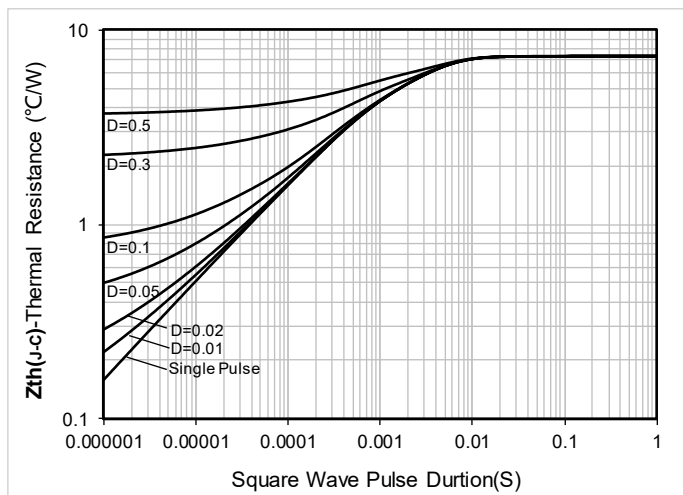


Figure 13. Maximum Transient Thermal Impedance

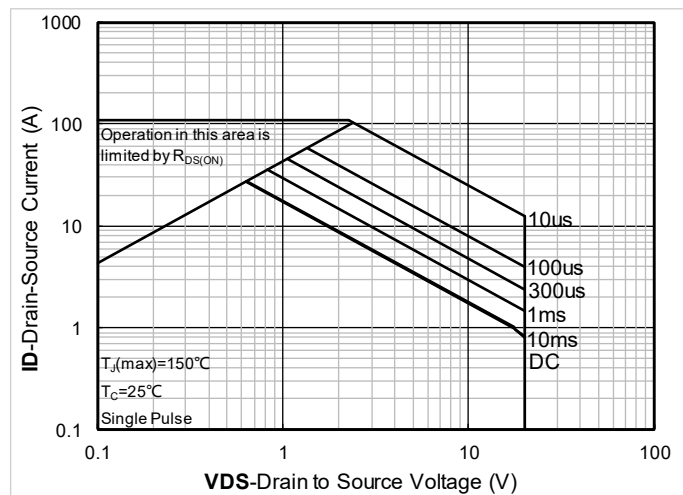


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms

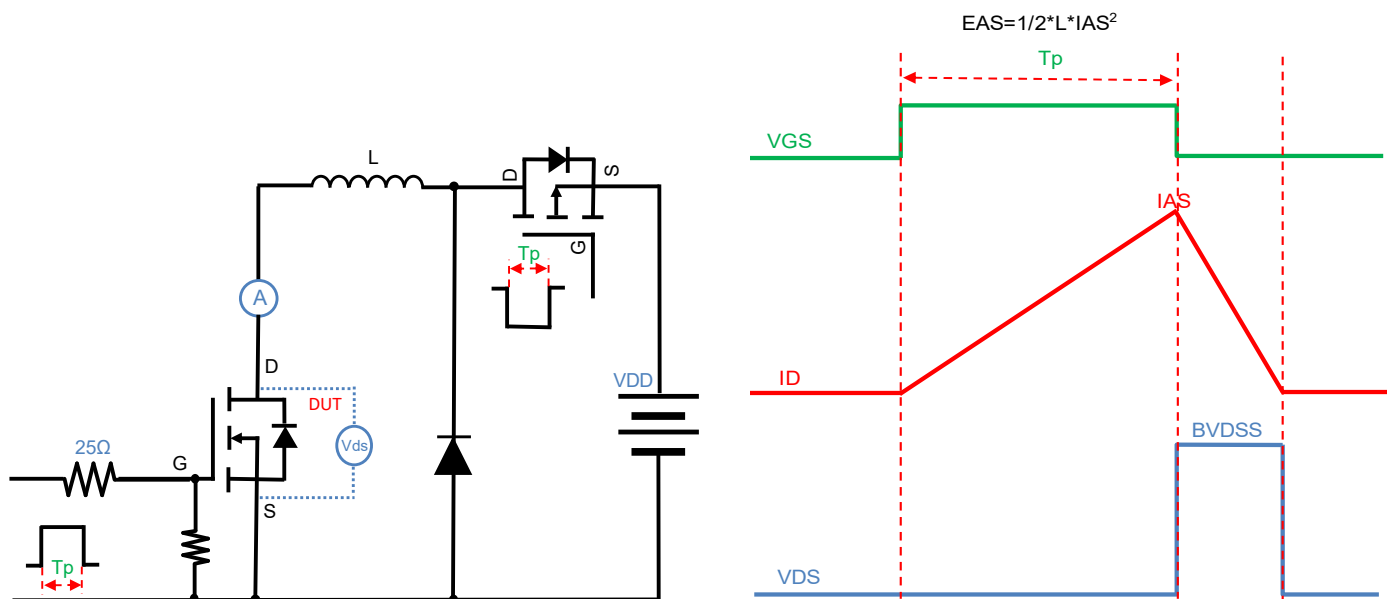


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

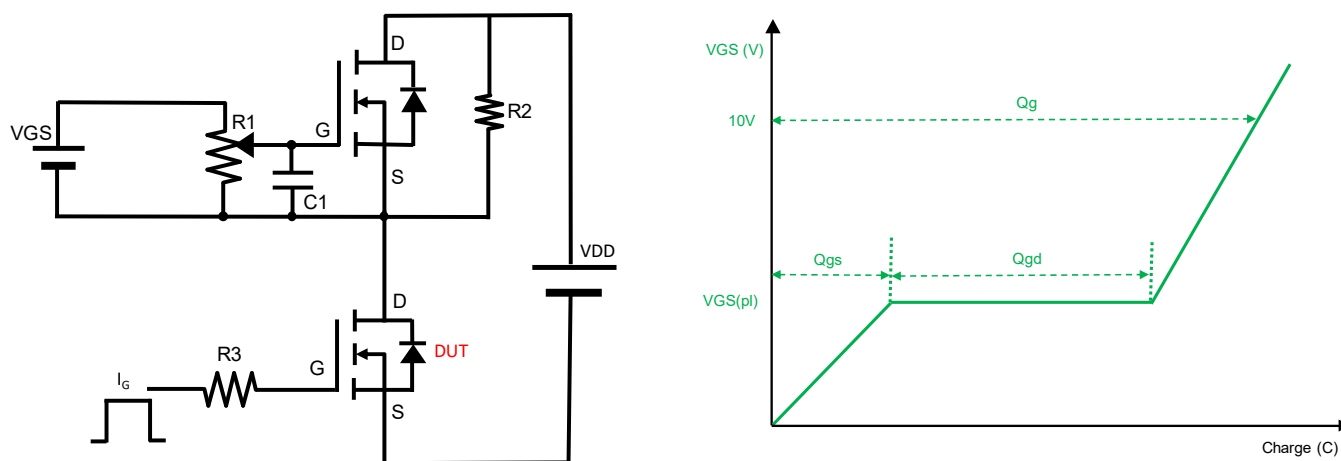


Figure B. Gate Charge Test Circuit & Waveform

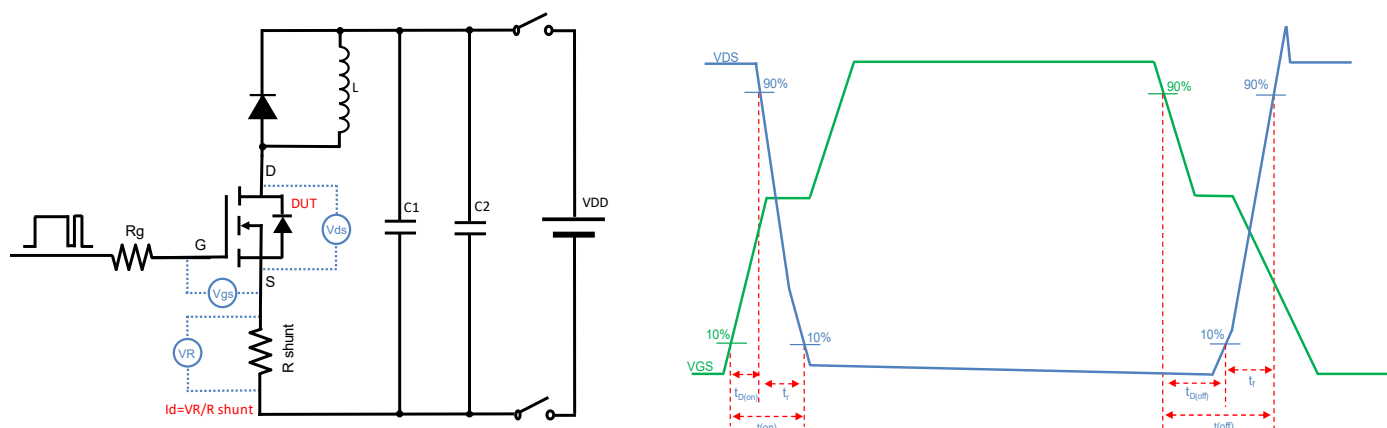


Figure C. Resistive Switching Test Circuit & Waveform

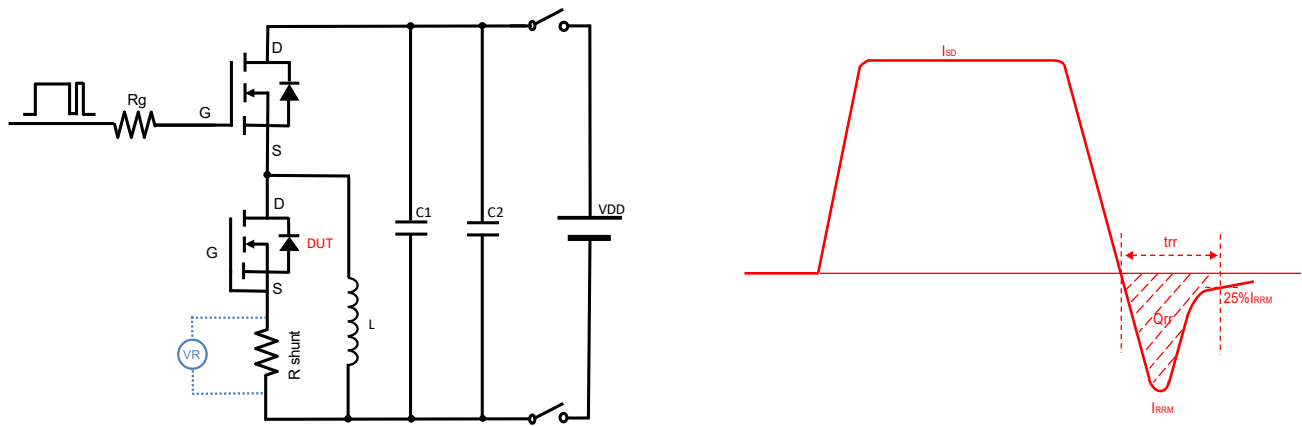
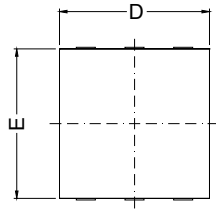


Figure D. Diode Recovery Test Circuit & Waveform

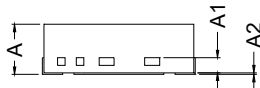


YJQT015N02AQ

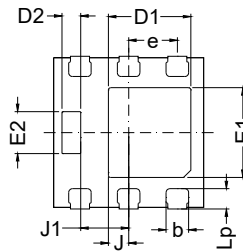
■ DFN2020-6L-H-0.65MM Package Information



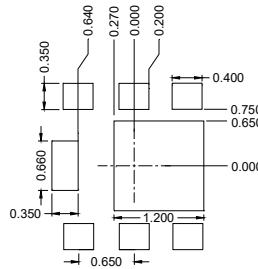
Top View
正面视图



Side View
侧面视图



Bottom View
背面视图



Suggested Solder Pad Layout
Top View

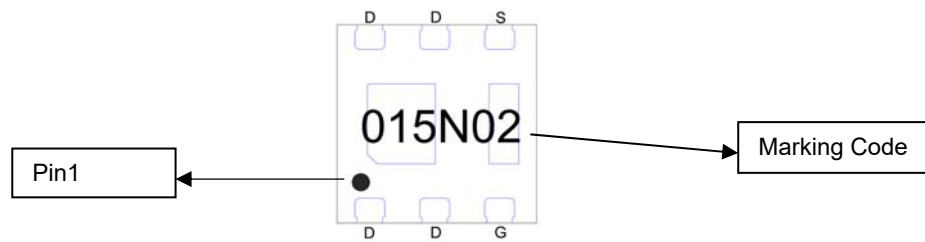
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	1.90	2.00	2.10
E	1.90	2.00	2.10
A	0.55	0.65	0.75
A1	0.20 BSC		
A2	0	-	0.10
D1	1.00	1.10	1.20
D2	0.20	0.25	0.35
E1	1.10	1.20	1.30
E2	0.51	0.56	0.66
Lp	0.20	0.25	0.35
J	0.27 BSC		
J1	0.64 BSC		
b	0.20	0.30	0.40
e	0.65 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. 015N02 is marking code
4. Body color: Black



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